

September 1995

Features

- 3 Micron Radiation Hardened SOS CMOS
- Total Dose 200K RAD (Si)
- SEP Effective LET No Upsets: $>100 \text{ MEV-cm}^2/\text{mg}$
- Single Event Upset (SEU) Immunity $< 2 \times 10^{-9}$ Errors/Bit-Day (Typ)
- Dose Rate Survivability: $>1 \times 10^{12}$ RAD (Si)/s
- Dose Rate Upset $>10^{10}$ RAD (Si)/s, 20ns Pulse
- Latch-Up Free Under Any Conditions
- Military Temperature Range: -55°C to $+125^\circ\text{C}$
- Significant Power Reduction Compared to LSTTL ICs
- DC Operating Voltage Range: 4.5V to 5.5V
- Input Logic Levels
 - $V_{IL} = 30\%$ of VCC Max
 - $V_{IH} = 70\%$ of VCC Min
- Input Current Levels $I_i \leq 5\mu\text{A}$ at VOL, VOH

Description

The Intersil HCS125MS is a Radiation Hardened quad three-state buffer, each having its own output enable input. A high level on the enable input puts the output in a high impedance state.

The HCS125MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of radiation hardened, high-speed, CMOS/SOS Logic Family.

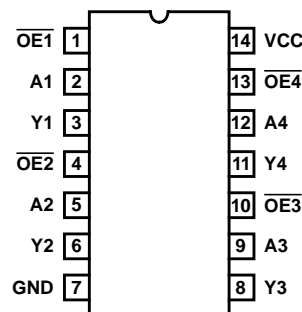
The HCS125MS is supplied in a 14 lead Ceramic flatpack (K suffix) or a SBDIP Package (D suffix).

Ordering Information

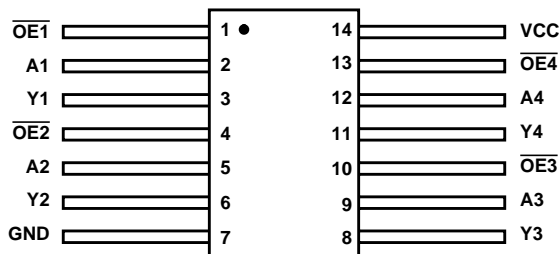
PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
HCS125DMSR	-55°C to $+125^\circ\text{C}$	Intersil Class S Equivalent	14 Lead SBDIP
HCS125KMSR	-55°C to $+125^\circ\text{C}$	Intersil Class S Equivalent	14 Lead Ceramic Flatpack
HCS125D/ Sample	$+25^\circ\text{C}$	Sample	14 Lead SBDIP
HCS125K/ Sample	$+25^\circ\text{C}$	Sample	14 Lead Ceramic Flatpack
HCS125HMSR	$+25^\circ\text{C}$	Die	Die

Pinouts

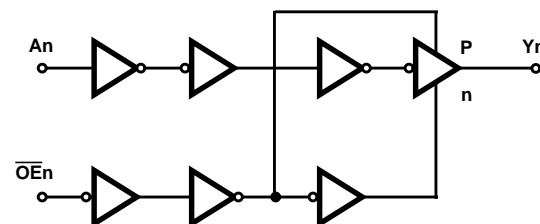
14 LEAD CERAMIC DUAL-IN-LINE
METAL SEAL PACKAGE (SBDIP)
MIL-STD-1835 CDIP2-T14, LEAD FINISH C
TOP VIEW



14 LEAD CERAMIC METAL SEAL
FLATPACK PACKAGE (FLATPACK)
MIL-STD-1835 CDFP3-F14, LEAD FINISH C
TOP VIEW



Functional Diagram



TRUTH TABLE

INPUTS		OUTPUT
An	$\overline{\text{OE}}_n$	Yn
H	L	H
L	L	L
X	H	Z

L = Low, H = High, X = Don't Care, Z = High Impedance

Specifications HCS125MS

Absolute Maximum Ratings

Supply Voltage -0.5V to +7.0V
 Input Voltage Range, All Inputs -0.5V to VCC +0.5V
 DC Input Current, Any One Input ±10mA
 DC Drain Current, Any One Output ±35mA
 Storage Temperature Range (TSTG) -65°C to +150°C
 Lead Temperature (Soldering 10sec) +265°C
 Junction Temperature (TJ) +175°C
 ESD Classification Class 1
 (All Voltage Reference to the VSS Terminal)

Reliability Information

Thermal Resistance θ_{JA} θ_{JC}
 SBDIP Package 74°C/W 24°C/W
 Ceramic Flatpack Package 116°C/W 30°C/W
 Maximum Package Power Dissipation at +125°C Ambient
 SBDIP Package 0.68W
 Ceramic Flatpack Package 0.43W
 If device power exceeds package dissipation capability, provide heat sinking or derate linearly at the following rate:
 SBDIP Package 13.5mW/°C
 Ceramic Flatpack Package 8.6mW/°C
 Gate Count 20 Gates

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Operating Conditions

Supply Voltage Range +4.5V to +5.5V
 Input Rise and Fall Time at 4.5V VCC (tr, tf) 100ns/V Max.
 Operating Temperature Range -55°C to +125°C
 Input High Voltage VCC to 70% of VCC
 Input Low Voltage 0V to 30% of VCC

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	GROUP A SUB- GROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Supply Current	ICC	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	40	µA
			2, 3	+125°C, -55°C	-	750	µA
Output Current (Source)	IOH	VCC = 4.5V, VIH = 4.5V, VOUT = VCC -0.4V, VIL = 0V, (Note 2)	1	+25°C	-7.2	-	mA
			2, 3	+125°C, -55°C	-6.0	-	mA
Output Current (Sink)	IOL	VCC = 4.5V, VIH = 4.5V, VOUT = 0.4V, VIL = 0V, (Note 2)	1	+25°C	7.2	-	mA
			2, 3	+125°C, -55°C	6.0	-	mA
Output Voltage High	VOH	VCC = 5.5V, VIH = 3.85V, VIL = 1.65V, IOH = -50µA	1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
		VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, IOH = -50µA	1, 2, 3	+25°C, +125°C, -55°C	VCC -0.1	-	V
Output Voltage Low	VOL	VCC = 5.5V, VIH = 3.85V, VIL = 1.65V, IOL = 50µA	1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
		VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, IOL = 50µA	1, 2, 3	+25°C, +125°C, -55°C	-	0.1	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	1	+25°C	-	±0.5	µA
			2, 3	+125°C, -55°C	-	±5.0	µA
Three-State Output Leakage Current	IOZ	VCC = 5.5V, Force Voltage = 0V or VCC	1	+25°C	-	±1.0	µA
			2, 3	+125°C, -55°C	-	±50	µA
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, (Note 3)	7, 8A, 8B	+25°C, +125°C, -55°C	-	-	V

NOTES:

1. All voltages reference to device GND.
2. Force/Measure functions may be interchanged.
3. For functional tests, $VO \geq 4.0V$ is recognized as a logic "1", and $VO \leq 0.5V$ is recognized as a logic "0".

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TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTES 1, 2) CONDITIONS	GROUP A SUB- GROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Propagation Delay Input to Y	TPHL TPLH	VCC = 4.5V, VIH = 4.5V, VIL = 0V	9	+25°C	2	21	ns
			10, 11	+125°C, -55°C	2	25	ns
Enable Delay OE to Y	TPZL TPZH	VCC = 4.5V, VIH = 4.5V, VIL = 0V	9	+25°C	2	25	ns
			10, 11	+125°C, -55°C	2	30	ns
Disable Delay OE to Y	TPLZ TPHZ	VCC = 4.5V, VIH = 4.5V, VIL = 0V	9	+25°C	2	25	ns
			10, 11	+125°C, -55°C	2	30	ns

NOTES:

1. All voltages referenced to device GND.
2. AC measurements assume RL = 500Ω, CL = 50pF, Input TR = TF = 3ns.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Capacitance Power Dissipation	CPD	VCC = 5.0V, VIH = 5.0V, VIL = 0V, f = 1MHz	1	+25°C	-	60	pF
			1	+125°C, -55°C	-	90	pF
Input Capacitance	CIN	VCC = 5.0V, VIH = 5.0V, VIL = 0V, f = 1MHz	1	+25°C	-	10	pF
			1	+125°C, -55°C	-	10	pF
Output Capacitance	COUT	VCC = 5.0V, VIH = 5.0V, VIL = 0V, f = 1MHz	1	+25°C	1	20	pF
			1	+125°C, -55°C	1	20	pF
Output Transition Time	TTHL TTLH	VCC = 4.5V, VIH = 4.5V, VIL = 0V	1	+25°C	1	15	ns
			1	+125°C, -55°C	1	22	ns

NOTE:

1. The parameters listed in Table 3 are controlled via design or process parameters. Min and Max Limits are guaranteed but not directly tested. These parameters are characterized upon initial design release and upon design changes which affect these characteristics.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	TEMPERATURE	200K RAD LIMITS		UNITS
				MIN	MAX	
Supply Current	ICC	VCC = 5.5V, VIN = VCC or GND	+25°C	-	0.75	mA
Output Current (Source)	IOH	VCC = VIH = 4.5V, VOUT = VCC - 0.4V, VIL = 0	+25°C	-6.0	-	mA
Output Current (Sink)	IOL	VCC = VIH = 4.5V, VOUT = 0.4V, VIL = 0	+25°C	6.0	-	mA

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TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	TEMPERATURE	200K RAD LIMITS		UNITS
				MIN	MAX	
Output Voltage High	VOH	VCC = 5.5V, VIH = 3.85V, VIL = 1.65V, IOH = -50μA	+25°C	VCC -0.1	-	V
		VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, IOH = -50μA	+25°C	VCC -0.1	-	V
Output Voltage Low	VOL	VCC = 5.5V, VIH = 3.85V, VIL = 1.65V, IOL = 50μA	+25°C	-	0.1	V
		VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, IOL = 50μA	+25°C	-	0.1	V
Input Leakage Current	IIN	VCC = 5.5V, VIN = VCC or GND	+25°C	-	±5	μA
Three-State Output Leakage Current	IOZ	VCC = 5.5V, Force Voltage = 0V or VCC	+25°C	-	±50	μA
Noise Immunity Functional Test	FN	VCC = 4.5V, VIH = 3.15V, VIL = 1.35V, (Note 2)	+25°C	-	-	V
Propagation Delay Input to Y	TPHL TPLH	VCC = 4.5V, VIH = 4.5V, VIL = 0V	+25°C	2	25	ns
Enable Delay OE to Y	TPZL TPZH	VCC = 4.5V, VIH = 4.5V, VIL = 0V	+25°C	2	30	ns
Disable Delay OE to Y	TPLZ TPHZ	VCC = 4.5V, VIH = 4.5V, VIL = 0V	+25°C	2	30	ns

NOTES:

1. All voltages referenced to device GND.
2. For functional tests, $VO \geq 4.0V$ is recognized as a logic "1", and $VO \leq 0.5V$ is recognized as a logic "0".

TABLE 5. BURN-IN AND OPERATING LIFE TEST, DELTA PARAMETERS (+25°C)

PARAMETER	GROUP B SUBGROUP	DELTA LIMIT
ICC	5	+12μA
IOL/IOH	5	-15% of 0 Hour
IOZ	5	±200nA

Specifications HCS125MS

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUPS		METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Preburn-In)		100%/5004	1, 7, 9	ICC, IOL/H, IOZL/H
Interim Test I (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H, IOZL/H
Interim Test II (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H, IOZL/H
PDA		100%/5004	1, 7, 9, Deltas	
Interim Test III (Postburn-In)		100%/5004	1, 7, 9	ICC, IOL/H, IOZL/H
PDA		100%/5004	1, 7, 9, Deltas	
Final Test		100%/5004	2, 3, 8A, 8B, 10, 11	
Group A (Note 1)		Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	Sample/5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
	Subgroup B-6	Sample/5005	1, 7, 9	
Group D		Sample/5005	1, 7, 9	

NOTE:

1. Alternate group A testing in accordance with Method 5005 of Mil-Std-883 may be exercised.

TABLE 7. TOTAL DOSE IRRADIATION

CONFORMANCE GROUPS	METHOD	TEST		READ AND RECORD	
		PRE RAD	POST RAD	PRE RAD	POST RAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4 (Note 1)

NOTE:

1. Except FN test which will be performed 100% go/no-go.

TABLE 8. STATIC AND DYNAMIC BURN-IN TEST CONNECTIONS

OPEN	GROUND	1/2 VCC = 3V ± 0.5V	VCC = 6V ± 0.5V	OSCILLATOR	
				50kHz	25kHz
STATIC I BURN-IN (Note 1)					
3, 6, 8, 11	1, 2, 4, 5, 7, 9, 10, 12, 13	-	14	-	-
STATIC II BURN-IN (Note 1)					
3, 6, 8, 11	7	-	1, 2, 4, 5, 9, 10, 12, 13, 14	-	-
DYNAMIC BURN-IN (Note 2)					
-	7	3, 6, 8, 11	14	1, 2, 4, 5, 9, 10, 12, 13	-

NOTES:

1. Each pin except VCC and GND will have a series resistor of 10K ± 5%.
2. Each pin except VCC and GND will have a series resistor of 1K ± 5%.

TABLE 9. IRRADIATION TEST CONNECTIONS

OPEN	GROUND	VCC = 5V ± 0.5V
3, 6, 8, 11	7	1, 2, 4, 5, 9, 10, 12, 13, 14

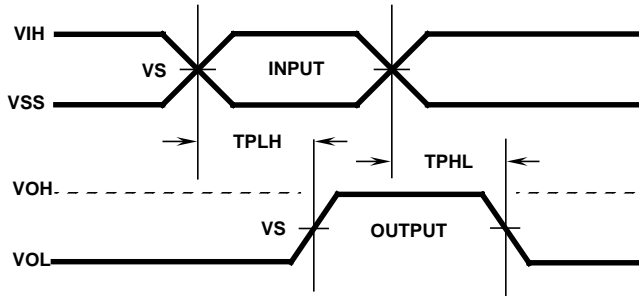
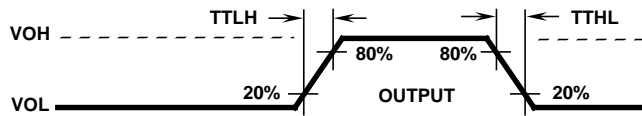
NOTE: Each pin except VCC and GND will have a resistor of 47KΩ ± 5% for irradiation testing. Group E, Subgroup 2, sample size is 4 dice/wafer 0 failures.

Intersil Space Level Product Flow - 'MS'

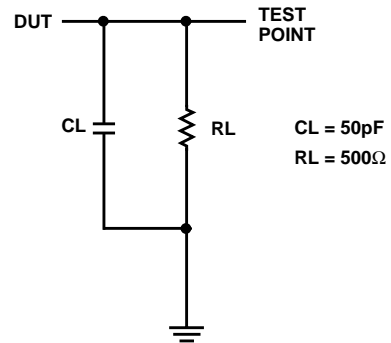
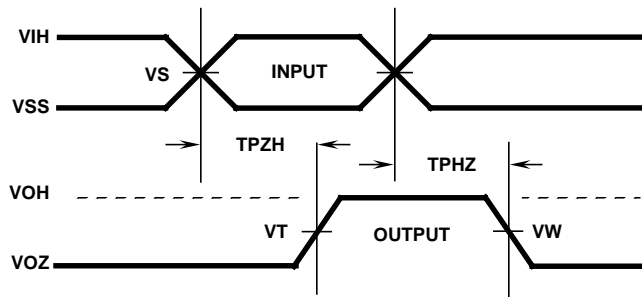
Wafer Lot Acceptance (All Lots) Method 5007 (Includes SEM)	100% Interim Electrical Test 1 (T1)
GAMMA Radiation Verification (Each Wafer) Method 1019, 4 Samples/Wafer, 0 Rejects	100% Delta Calculation (T0-T1)
100% Nondestructive Bond Pull, Method 2023	100% Static Burn-In 2, Condition A or B, 24 hrs. min., +125°C min., Method 1015
Sample - Wire Bond Pull Monitor, Method 2011	100% Interim Electrical Test 2 (T2)
Sample - Die Shear Monitor, Method 2019 or 2027	100% Delta Calculation (T0-T2)
100% Internal Visual Inspection, Method 2010, Condition A	100% PDA 1, Method 5004 (Notes 1 and 2)
100% Temperature Cycle, Method 1010, Condition C, 10 Cycles	100% Dynamic Burn-In, Condition D, 240 hrs., +125°C or Equivalent, Method 1015
100% Constant Acceleration, Method 2001, Condition per Method 5004	100% Interim Electrical Test 3 (T3)
100% PIND, Method 2020, Condition A	100% Delta Calculation (T0-T3)
100% External Visual	100% PDA 2, Method 5004 (Note 2)
100% Serialization	100% Final Electrical Test
100% Initial Electrical Test (T0)	100% Fine/Gross Leak, Method 1014
100% Static Burn-In 1, Condition A or B, 24 hrs. min., +125°C min., Method 1015	100% Radiographic, Method 2012 (Note 3)
	100% External Visual, Method 2009
	Sample - Group A, Method 5005 (Note 4)
	100% Data Package Generation (Note 5)

NOTES:

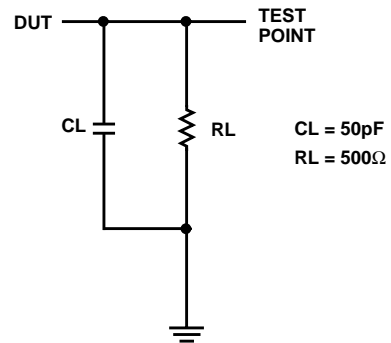
- Failures from Interim electrical test 1 and 2 are combined for determining PDA 1.
- Failures from subgroup 1, 7, 9 and deltas are used for calculating PDA. The maximum allowable PDA = 5% with no more than 3% of the failures from subgroup 7.
- Radiographic (X-Ray) inspection may be performed at any point after serialization as allowed by Method 5004.
- Alternate Group A testing may be performed as allowed by MIL-STD-883, Method 5005.
- Data Package Contents:
 - Cover Sheet (Intersil Name and/or Logo, P.O. Number, Customer Part Number, Lot Date Code, Intersil Part Number, Lot Number, Quantity).
 - Wafer Lot Acceptance Report (Method 5007). Includes reproductions of SEM photos with percent of step coverage.
 - GAMMA Radiation Report. Contains Cover page, disposition, Rad Dose, Lot Number, Test Package used, Specification Numbers, Test equipment, etc. Radiation Read and Record data on file at Intersil.
 - X-Ray report and film. Includes penetrometer measurements.
 - Screening, Electrical, and Group A attributes (Screening attributes begin after package seal).
 - Lot Serial Number Sheet (Good units serial number and lot number).
 - Variables Data (All Delta operations). Data is identified by serial number. Data header includes lot number and date of test.
 - The Certificate of Conformance is a part of the shipping invoice and is not part of the Data Book. The Certificate of Conformance is signed by an authorized Quality Representative.

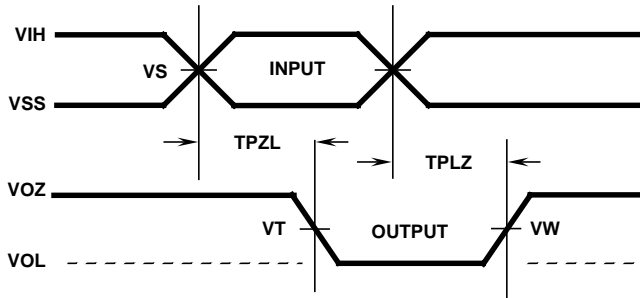
Propagation Delay Timing Diagram**Transition Timing Diagram****VOLTAGE LEVELS**

PARAMETER	HCS	UNITS
VCC	4.50	V
V_{IH}	4.50	V
V_S	2.25	V
V_{IL}	0	V
GND	0	V

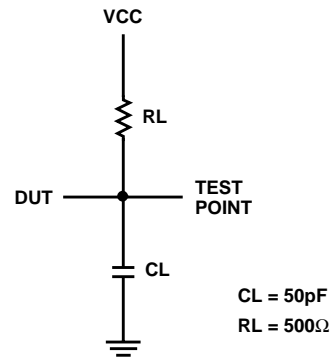
Propagation Delay Load Circuit**Three-State High Timing Diagrams****THREE-STATE HIGH VOLTAGE LEVELS**

PARAMETER	HCS	UNITS
VCC	4.50	V
V_{IH}	4.50	V
V_S	2.25	V
V_T	2.25	V
V_W	3.60	V
GND	0	V

Three-State High Load Circuit

Three-State Low Timing Diagrams**THREE-STATE LOW VOLTAGE LEVELS**

PARAMETER	HCS	UNITS
VCC	4.50	V
VIH	4.50	V
VS	2.25	V
VT	2.25	V
VW	0.90	V
GND	0	V

Three-State Low Load Circuit

$C_L = 50\text{pF}$
 $R_L = 500\Omega$

Die Characteristics

DIE DIMENSIONS:

92 x 91 (mils)
2.34 x 2.31 (mm)

METALLIZATION:

Type: AlSi
Thickness: $11\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

GLASSIVATION:

Type: SiO_2
Thickness: $13\text{k}\text{\AA} \pm 2.6\text{k}\text{\AA}$

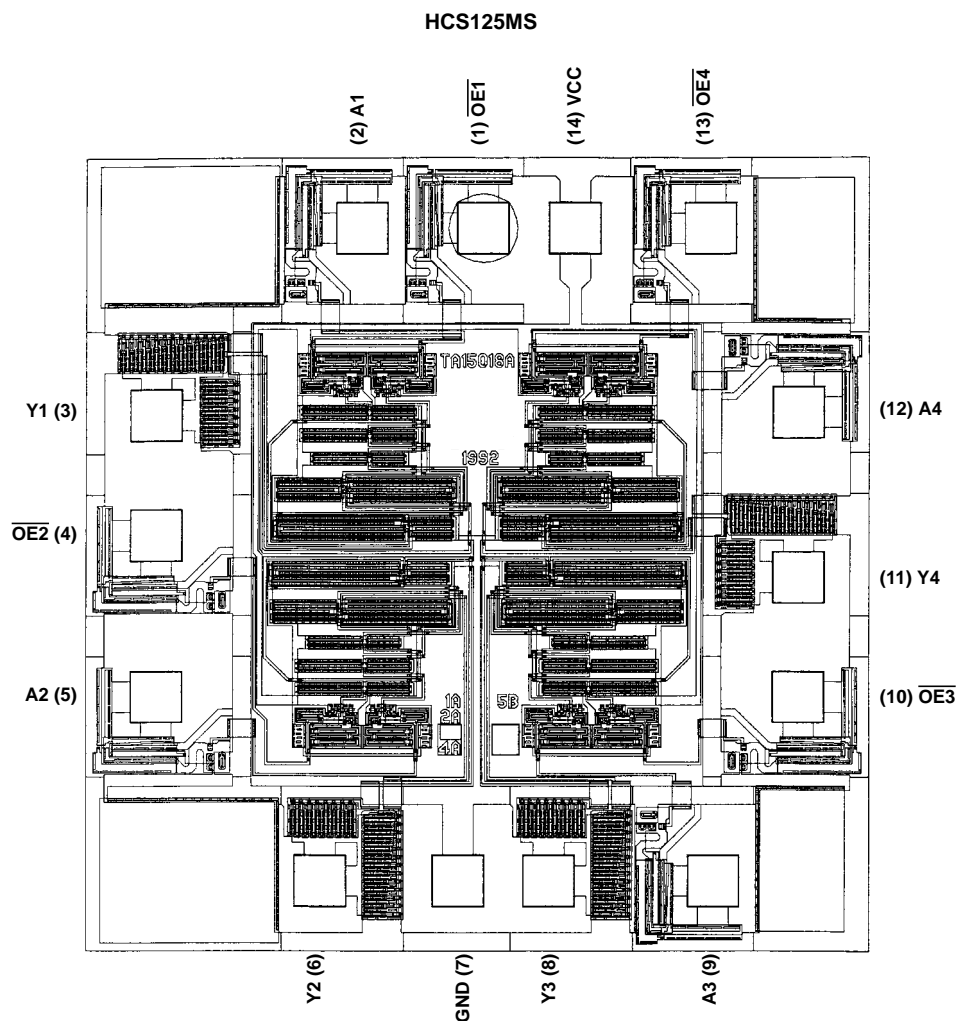
WORST CASE CURRENT DENSITY:

$<2.0 \times 10^5 \text{ A/cm}^2$

BOND PAD SIZE:

4 x 4 (mils)
100 x 100 (μm)

Metallization Mask Layout



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